Retaining System for Retaining and Holding a Wafer

Abstract

This invention relates to a retaining system for retaining and holding a wafer for processing the wafer with a holding surface for placing the wafer on a support surface of the wafer and holding means for holding the wafer, whereby because of the holding means holding extremely thin wafers on the holding surface of the wafer, the smallest possible local distortions of the wafer are achieved.

Figure 3a.